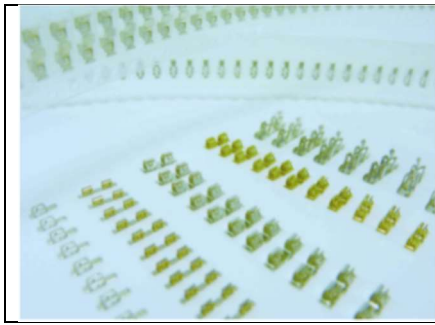


SMD GROUNDING CLIP

Kitagawa series: OGCP

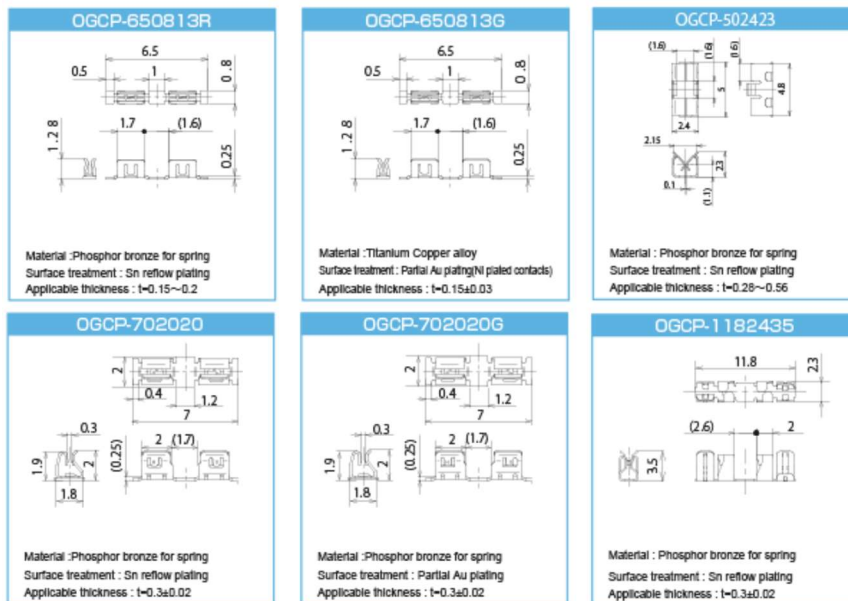


- OGCP-421510 offers low height design.
- OGCP-1182435 resistant to side slide loading.
- OGCP-702020(G) provides improved workability.

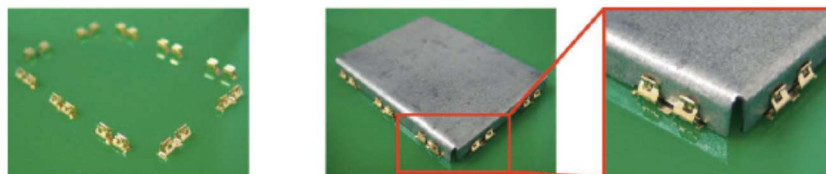
MATERIAL

Part Number	Material	Surface Treatment	Applicable Thickness
OGCP-1182435	Phosphor bronze for spring	Sn reflow plating	t=0.3 ±0.02
OGCP-650813R	Phosphor bronze for spring	Sn reflow plating	t=0.15 ~ 0.2
OGCP-650813G	Titanium copper alloy	Partial Au plating (Ni plated contacts)	t=0.15 ±0.03
OGCP-502423	Phosphor bronze for spring	Sn reflow plating	t=0.28 ~ 0.56
OGCP-702020	Phosphor bronze for spring	Sn reflow plating	t=0.3 ±0.02
OGCP-702020G	Phosphor bronze for spring	Partial Au plating	t=0.3 ±0.02

DIMENSIONS (mm)



● Installation example:OGCP-702020(G)



Shielding can fixing not guaranteed if only the clip is used. Resistance against drop impact varies according to weight of shielding can.